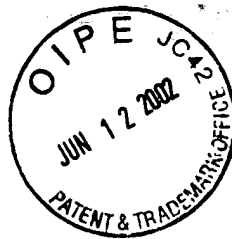


Practitioner's Docket No. 4492P1072US



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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:  
Application No.:  
Filed:  
Examiner:  
Group No.:  
For:

Batz, Robert W., Jr.

09/390,501

09/03/1999

Erica Smith-Hicks

1741

METHODS FOR PLATING SEMICONDUCTOR WORKPIECES  
USING A WORKPIECE-ENGAGING ELECTRODE ASSEMBLY  
WITH SEALING BOOT

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I hereby certify that the attached correspondence comprising:

Issue Fee Transmittal  
Formal Drawings (38 pgs)  
Rule 312 Amendment with Application Data Sheet  
Change of Correspondence Address  
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Robert B. Polit (33,993)